

a contact tip structure secured to an end of the <u>freestanding</u> resilient elongate element.

- 95. 1 The interconnection component, according to claim 87 wherein: 2 said freestanding resilient elongate element comprises a core element, and wherein the core element has a diameter in the range of from 0.25 to 10 mils. 3 96. The interconnection component, according to claim 87 wherein: said freestanding resilient elongate element comprises a core element, and wherein the core element has a diameter in the range of from 0.5 to 3 mils. 97. The interconnection component, according to claim 87 wherein: 1 2 said freestanding resilient elongate element comprises a core element, and wherein the core element has a length in the range of from 10 mils to 500 mils. 3 98. The interconnection component, according to claim 87 wherein: 1 said freestanding resilient elongate element comprises a shell, and wherein the shell 2 has at least one layer which comprises a material which is selected for its ability to provide mechanical properties selected from the group consisting 5 of spring properties resiliency yield strength and compliance for the resilient elongate element. 6
- 1 101. (New) The interconnection component, according to claim 87 wherein:

 2 said freestanding resilient elongate element comprises a shell, and wherein the shell

 3 has at least one layer which comprises a material selected from the group

 4 consisting of nickel, iron, and cobalt.

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	1	102.	The interconnection component, according to claim 87 wherein:
	2		said freestanding resilient elongate element comprises a shell, and wherein the shell
	3		has at least one layer which comprises a material selected from the group
1	4		consisting of copper, nickel, cobalt, tin, boron, phosphorous, chromium,
J.) 5 ⁰		tungsten, molybdenum, bismuth, indium, cesium, antimony, gild, silver,
J. W.	6		rhodium, palladium, platinum, lead, and ruthenium.
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	1	103.	The interconnection component, according to claim 87 wherein:
	2		said freestanding resilient elongate element comprises a core element and a shell,
	3		and wherein the core element comprises gold and the shell comprises a
	4		material selected from the group consisting of nickel and cobalt.
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Sub	(1)L	106.	An electronics assembly comprising:
	2		a substrate;
1	3		a <u>freestanding</u> resilient elongate element having a first end secured to the substrate;
ana	4		and a contact tip structure secured to the second end of the <u>freestanding</u>
7	5		resilient elongate element opposing the first end.
•	1	107.	The electronics assembly, according to claim 106 further comprising:
**	2		a plurality of <u>freestanding</u> resilient elongate elements, each having a first end
	3		secured to the substrate; and a plurality of contact tip structures, each
	4		secured to a respective end of the respective <u>freestanding</u> resilient elongate
	5		element opposing a respective first end thereof.
	1	108.	The electronics assembly, according to claim 106 wherein:
	2		the contact tip structure is separately fabricated and mounted to the freestanding
	3		resilient elongate element.

	1	109.	The electronic assembly, according to claim 108 wherein:
	2		the freestanding resilient elongate element has a relatively flexible core element and
5	3		a layer on the relatively flexible core element.
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	\mathcal{L}_1	110.	The electronic assembly, according to claim/108 wherein:
	2		the <u>freestanding</u> resilient elongate element has a relatively flexible core and a layer,
	3		on the relatively flexible core element, of a material selected from the group
	4		consisting of nickel, an alloy of nickel, cobalt, an alloy of cobalt and an
	5		alloy of nickel and cobalt.
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	1	112.	The electronics assembly, according to claim 106 wherein:
	2		the <u>freestanding</u> resilient elongate element has a core element and a shell;
	3		the core element is readily-shaped and comprises a material selected form the group
	4		consisting of:
· W	5		(a) gold, aluminum and copper with small amounts of beryllium,
	6		cadmium, silicon and magnesium, and
	7		(b) metals of the platinum group, and
	8		(c) lead, tin, and indium.
	1	113.	The electronics assembly, according to claim 109 wherein:
	2		the layer comprises a material which is selected for its ability to provide mechanical
	3		properties selected from the group consisting of spring properties, resiliency
	4		yield strength and compliance for the freestanding resilient elongate element.
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